

2016

Technology Seminar



Inspection and Testing for Industry 4.0

date. time. . .

19 **MAY** **9:00**
2016 **16:00**

venue.

Eastin Hotel, Penang
Queensbay Mall, Bayan Lepas

Agenda

- 9:20~9:40** Registration
Registration and Morning snack

- 10:00~10:20** Welcome Note
Seminar opening

- 10:20~10:50** 3D SPI
Speed and Automation in 3D SPI

- 10:50~11:40** 3D AOI
Accurate 3D solder fillet inspection

- 11:40~12:00** Product Demo
Live on-site hands-on demo

- 12:00~13:30** Lunch
Networking and refreshments

- 13:30~14:20** AXI, CT Inspection
New CT Applications and NPI Solutions

- 14:20~15:00** Multi-core ICT Testing
Introducing all-new TR5001 SII Series ICT

- 15:00~15:30** YMS 4.0 for Industry 4.0

- 15:30~16:00** Q&A & Pop Quiz

- 16:00** Tea Break & Demo

New Products



TR7007Q 3D SPI
Stop-and-go 3D SPI with 4-way digital fringe pattern projection 6 µm optical resolution for 0250125mm chips.



TR7700Q 3D AOI
Precise Stop-and-go 3D AOI with 4-way digital fringe pattern projection and 3D Solder Fillet inspection.



TR7600XLL SII 3D AXI
New 3D X-ray Inspection System with high-speed inspection and built-in CT function for detailed 3D solder joint review.



TR5001 SII Series ICT
New Multi-Core Parallel ICT offers improved accuracy, test speed and throughput while reducing operator workload.

To register, please contact:
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